

Mechanisms of reduction in hole concentration in Al-doped 4H-SiC by electron irradiation

From the temperature dependence of the hole concentration $p(T)$ in Al-doped 4H-SiC irradiated with 4.6 MeV electrons with $2.6 \times 10^{14} \text{ cm}^{-2}$, we reported that the density of one acceptor species with $E_V + 200 \text{ meV}$ was significantly reduced while the density of the other acceptor with $E_V + 350 \text{ meV}$ was slightly decreased, where E_V is the valence band top. From photoluminescence and Hall-effect measurements, the shallow acceptor was ascribed to an Al atom at a Si site (Al_{Si}). On the other hand, the origin of the deep acceptor is not assigned.

The possible mechanisms of the reduction in the $p(T)$ by the irradiation are as follows; (1) a decrease in the Al acceptor density because the Al_{Si} is moved into the interstitial site or because the bond between the Al_{Si} and the nearest neighbor C atom is broken, or (2) the creation of deep hole traps or donor-like defects.

A 10 μm -thick Al-doped 4H-SiC epilayer (doping density: $5 \times 10^{15} \text{ cm}^{-3}$) was used. The $p(T)$ was obtained by Hall-effect measurements.

One electron with $< 250 \text{ keV}$ can displace only the C atom, whereas one electron with $> 500 \text{ keV}$ is sufficient to displace the Al or Si atom. By irradiation with 200 keV electrons with $1 \times 10^{16} \text{ cm}^{-2}$, the decrement of the Al acceptor density is close to the increment of the unknown deep acceptor density. This suggests that the bond between the Al_{Si} and the nearest neighbor C atom is broken by the displacement of the C atoms, which results in a decrease in the Al acceptor density and an increase in the density of a complex ($\text{Al}_{\text{Si}}\text{-V}_{\text{C}}$) of the Al_{Si} and the nearest neighbor C vacancy. Therefore, the origin of the deep acceptor is considered to be $\text{Al}_{\text{Si}}\text{-V}_{\text{C}}$.

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